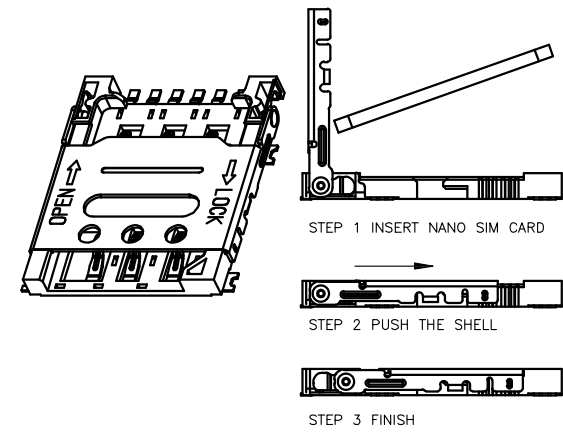
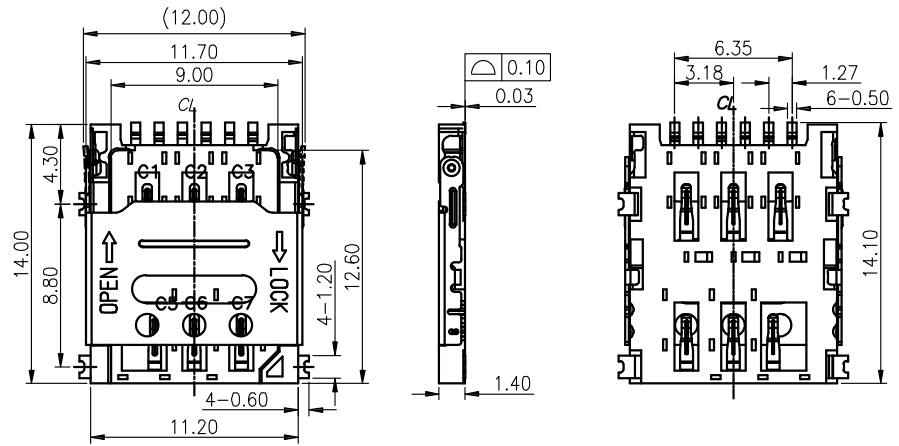


REV.	ECN.NO.	APPD.
A	/	/



***Electrical Characteristics:**
 Contact Current Rating:0.5 Amperes.
 Dielectric Withstanding Voltage:AC500V r.m.s.
 Insulation Resistance:1000 MΩ Minimum.
 Contact Resistance:100 mΩ Maximum.

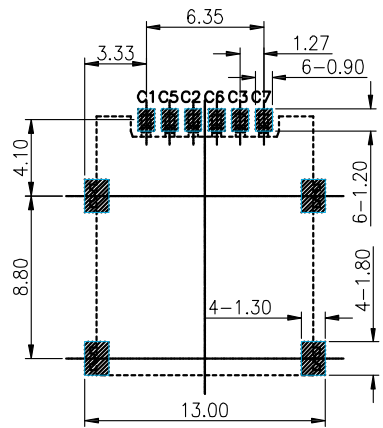
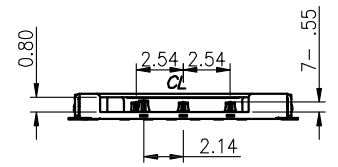
***Environmental:**
 Operating Temperature:-25°C~+90°C.

***Environmental:**
 Mating Cycles:5000~10,000 Insertions.

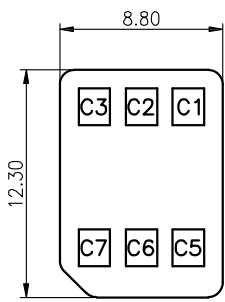
***Mechanical Characteristics:**
 Card Push Insertion/Out Force:1.4kgf. MAX
 Contact Separation Force:0.20kgf Minimum.

***Material:**
 Insulator:HI-Temp Plastic UL 94V-0 Rated.
 Contact:Copper Alloy(t=0.15mm).
 Shell:Stainless Steel(t=0.20mm).
 Spring:SWP.

SD5209-165-G68
 G: 半金G/Fu”
 6:LCP黑色



RECOMMENDED PCB LAYOUT
 TOLERANCE ±0.05
 SMT SOLDER AREA



PIN NO.	PIN NAME
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

TOLERANCE UNLESS OTHERWISE SPECIFIED		FLW 深圳市华联威电子科技有限公司			
.XXX ±0.10 .XX ±0.20 .X ±0.30		.X' ±3' .XX' ±2'		HUA LIAN WEI TECHNOLOGY ELECTRONICS CO;LTD.	
APPROVED		PART NAME:	手机NANO SIM卡座翻盖式6P镀镍 读卡器掀盖式卡槽铁壳卡座		
CHECKED		PART No:	SD5209-165-G68	C	
DRAWN	chenyiting	PROJECTION:	UNIT:	SCALE	SHEET
DATE	2023. 04. 19		mm	1:1	10F1
					REV. A